

L Number	Hits	Search Text	DB	Time stamp
11	273	card and (die near5 pad) and lead and chip and seal\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/17 08:56
12	5	(card and (die near5 pad) and lead and chip and seal\$3) and 235/492.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/17 08:56
14	525	((ic or (integrated adj2 circuit) or semiconductor or chip) adj3 (device or card)) and ((thermosetting or thermoplastic) and (die near5 pad) and lead and wir\$3 and (chip or module) and seal\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/17 08:58
15	14	((ic or (integrated adj2 circuit) or semiconductor or chip) adj3 (device or card)) same ((thermosetting or thermoplastic) same (die near5 pad) same lead same wir\$3 same (chip or module) same seal\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/17 08:59
13	4	235/492.ccls. and ((thermosetting or thermoplastic) and (die near5 pad) and lead and wir\$3 and (chip or module) and seal\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/17 08:59
-	474	235/488.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/17 08:55
-	150	((ic or smart) adj2 card) same seal\$3 same wir\$3 same resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/16 19:59
-	65	235/488.ccls. and cavity	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/16 21:31
-	2244	235/492.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/16 21:09
-	47	235/492.ccls. and seal\$3 same wir\$3 same resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/16 20:02
-	40	(235/492.ccls. and seal\$3 same wir\$3 same resin) not (235/488.ccls. and cavity)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/16 20:02
-	6	("5272326" "5598032" "5671525" "5946198" "6429385" "6459588").PN.	USPAT	2004/05/16 21:02
-	4	("5498388" "5612532" "5814890" "5866950").PN.	USPAT	2004/05/16 21:05
-	1	6433285.URPN.	USPAT	2004/05/16 21:05
-	12	("3702464" "4532419" "4794243" "D421597" "D445797" "D446525" "D452243" "6381143" "D457887" "6433285" "6483038" "D467586").PN.	USPAT	2004/05/16 21:07
-	191	235/492.ccls. and (method near5 manufactur\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/16 21:09

-	203	235/492.ccls. and cavity	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/16 21:38
-	5	235/492.ccls. and (die near5 pad) and lead and seal\$3	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/16 21:49
-	2	6431456.URPN.	USPÄT	2004/05/16 21:40
-	13	("4841134" "5581065" "5821614" "5870289" "5872353" "5915226" "5979771" "6009315" "6076737" "6240301" "6320751" "6431456" "6454164").PN.	USPAT	2004/05/16 21:41
-	29	((("11163256") or ("3254994") or ("2000236043") or ("1145959") or ("8156470") or ("6106887") or ("1111067") or ("5246186") or ("200048161") or ("6216305")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/16 21:50